## E010 | EXPERIMENTAL BOARD, PERFORATED

Experimental board in euro measurement.

**Technical Data:**
Without copper layer **| Material:** FR2 (Pertinax) **| Hole distance:** 2,54 mm **| Diameter of holes:** Ø approx. 1 mm **| Thickness:** approx. 1,5 mm **| Dimensions:** approx. 100 x 160 mm

## E011 | EXPERIMENTAL BOARD STRIP GRID

Flash-gold plated (better for soldering „leadfree").

**Technical Data:**
**One-side copper layer:** approx. 35 µm **| Material:** FR2 (Pertinax) **| Hole distance:** 2,54 mm **| Diameter of holes:** Ø approx. 1 mm **| Thickness:** approx. 1,5 mm **| Dimensions:** approx. 100 x 500 mm

## E012 | EXPERIMENTAL BOARD STRIP GRID

Flash-gold plated (better for soldering „leadfree").

**Technical Data:**
**One-side copper layer:** approx. 35 µm **| Material:** FR2 (Pertinax) **| Hole distance:** 2,54 mm **| Diameter of holes:** Ø approx. 1 mm **| Thickness:** approx. 1,5 mm **| Dimensions:** approx. 100 x 100 mm

## E013 | EXPERIMENTAL BOARD with 3 STRIP GRID

The strip raster is interrupted every 3rd hole, flash-gold plated (better for soldering „leadfree").

**Technical Data:**
**One-side copper layer:** approx. 35 µm **| Material:** FR2 (Pertinax) **| Hole distance:** 2,54 mm **| Diameter of holes:** Ø approx. 1 mm **| Thickness:** approx. 1,5 mm **| Dimensions:** approx. 100 x 160 mm

## F001 | PHOTOPOSITIVE COATED BOARD

Photopositive coated board for production of printed circuits for electronics.

**Technical Data:**
**One-side copper layer:** approx. 35 µm **| Material:** FR2 (Pertinax) **| Thickness:** approx. 1,5 mm **| Dimensions:** approx. 100 x 160 mm